

3.3V CMOS Static RAM 4 Meg (1M x 4-Bit)

Features

- 1M x 4 advanced high-speed CMOS Static RAM
- JEDEC Center Power / GND pinout for reduced noise
- Equal access and cycle times — Commercial and Industrial: 10/12/15ns
- Single 3.3V power supply
- One Chip Select plus one Output Enable pin
- Bidirectional data inputs and outputs directly LVTTL-compatible
- Low power consumption via chip deselect

Functional Block Diagram

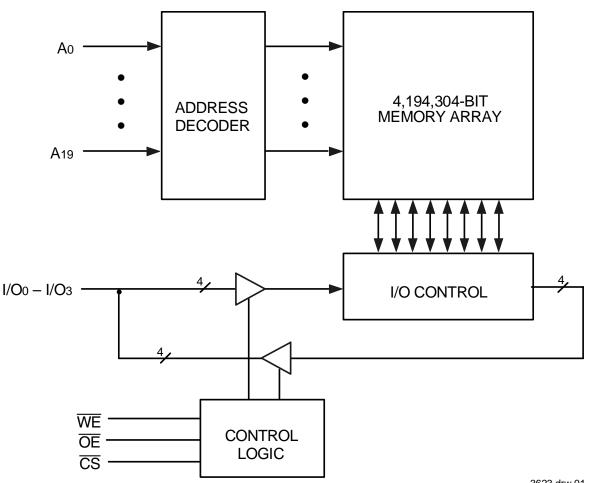
• Available in 32-pin, 400 mil plastic SOJ package.

Description

The IDT71V428 is a 4,194,304-bit high-speed Static RAM organized as 1M x 4. It is fabricated using IDT's high-perfomance, highreliability CMOS technology. This state-of-the-art technology, combined with innovative circuit design techniques, provides a costeffective solution for high-speed memory needs.

The IDT71V428 has an output enable pin which operates as fast as 5ns, with address access times as fast as 10ns. All bidirectional inputs and outputs of the IDT71V428 are LVTTL-compatible and operation is from a single 3.3V supply. Fully static asynchronous circuitry is used, requiring no clocks or refresh for operation.

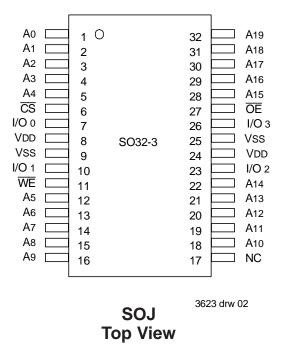
The IDT71V428 is packaged in a 32-pin, 400 mil Plastic SOJ.



3623 drw 01

SEPTEMBER 2004

Pin Configuration



Pin Description

A0 – A19	Address Inputs	Input
<u>cs</u>	Chip Select	Input
WE	Write Enable	Input
ŌĒ	Output Enable	Input
I/O0 - I/O3	Data Input/Output	I/O
Vdd	3.3V Power	Power
Vss	Ground	Gnd

3623 tbl 02

Capacitance

(TA = +25°C, f = 1.0MHz, SOJ package)

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
CIN	Input Capacitance	Vin = 3dV	7	pF
Cı/o	I/O Capacitance	Vout = 3dV	8	pF
				3623 tbl 03

NOTE:

1. This parameter is guaranteed by device characterization, but not production tested.

Truth Table^(1,2)

ĊŚ	ŌĒ	WE	I/O	Function
L	L	Н	DATAOUT	Read Data
L	Х	L	DATAIN	Write Data
L	Н	Н	High-Z	Output Disabled
Н	Х	Х	High-Z	Deselected - Standby (ISB)
VHC ⁽³⁾	Х	Х	High-Z	Deselected - Standby (ISB1)

NOTES:

1. $H = V_{IH}$, $L = V_{IL}$, x = Don't care.

2. VLC = 0.2V, VHC = VCC -0.2V.

3. Other inputs \geq VHC or \leq VLC.

3623 tbl 01

Symbol	Rating	Value	Unit
Vdd	Supply Voltage Relative to Vss	-0.5 to +4.6	V
Vin, Vout	Terminal Voltage Relative to Vss	-0.5 to Vdd+0.5	V
Tbias	Temperature Under Bias	-55 to +125	°C
Tstg	Storage Temperature	-55 to +125	٥C
Рт	Power Dissipation	1	W
Ιουτ	DC Output Current	50	mA
			3623 tbl 04

Absolute Maximum Ratings⁽¹⁾

NOTE:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Recommended Operating Temperature and Supply Voltage

Grade	Temperature	Vss	Vdd
Commercial	0°C to +70°C	0V	See Below
Industrial	–40°C to +85°C	0V	See Below

3623 tbl 05

3623 tbl 06

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vdd	Supply Voltage	3.0	3.3	3.6	۷
Vss	Ground	0	0	0	۷
Vін	Input High Voltage	2.0		VDD+0.3 ⁽¹⁾	۷
VIL	Input Low Voltage	-0.3(2)		0.8	۷

NOTES:

1. VIH (max.) = VDD+2V for pulse width less than 5ns, once per cycle.

2. VIL (min.) = -2V for pulse width less than 5ns, once per cycle.

DC Electrical Characteristics

(VDD = Min. to Max., Commercial and Industrial Temperature Ranges)

		IDT71V428		V428	
Symbol	Parameter	Test Condition	Min.	Max.	Unit
Lu	Input Leakage Current	$V_{DD} = Max., V_{IN} = V_{SS} to V_{DD}$		5	μA
Ilo	Output Leakage Current	$V_{DD} = Max., \overline{CS} = V_{IH}, V_{OUT} = V_{SS} to V_{DD}$		5	μA
Vol	Output Low Voltage	$I_{OL} = 8mA, V_{DD} = Min.$		0.4	V
Vон	Output High Voltage	Iон = -4mA, Vdd = Min.	2.4		V

3623 tbl 07

DC Electrical Characteristics^(1,2,3)

(VDD = Min. to Max., VLC = 0.2V, VHC = VDD - 0.2V)

			71V428S/L10		71V428S/L12		71V428S/L15		
Symbol	Parameter		Com'l.	Ind. ⁽⁵⁾	Com'l.	Ind.	Com'l.	Ind.	Unit
Icc			150	150	140	140	130	130	mA
			140	—	130	130	120	120	mA
ISB	$\frac{\text{Dynamic Standby Power Supply Current}}{\overline{\text{CS}} \geq \text{VHc, Outputs Open, Vdd} = \text{Max., } f = f_{\text{MAX}}^{(4)}$		60	60	50	50	40	40	mA
			40	—	35	35	30	30	mA
ISB1	Full Standby Power Supply Current (static)		20	20	20	20	20	20	mA
	$\overline{\text{CS}} \ge \text{V}_{\text{HC}}$, Outputs Open, VDD = Max., f = 0 ⁽⁴⁾	L	10	_	10	10	10	10	mA

NOTES:

1. All values are maximum guaranteed values.

2. All inputs switch between 0.2V (Low) and VDD - 0.2V (High).

3. Power specifications are preliminary.

4. fMAX = 1/tRC (all address inputs are cycling at fMAX); f = 0 means no address input lines are changing.

5. Standard power 10ns (S10) speed grade only.

3623 tbl 08

AC Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	1.5ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
AC Test Load	See Figure 1, 2 and 3

3623 tbl 09

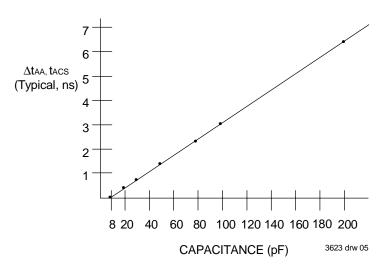
AC Test Loads



Figure 1. AC Test Load

* Including jig and scope capacitance.

Figure 2. AC Test Load (for tclz, tolz, tchz, tohz, tow, and twhz)





Commercial and Industrial Temperature Ranges

3.3V

3623 tbl 10

AC Electrical Characteristics (VDD = 3.3V ± 10%, Commercial and Industrial Temperature Ranges)

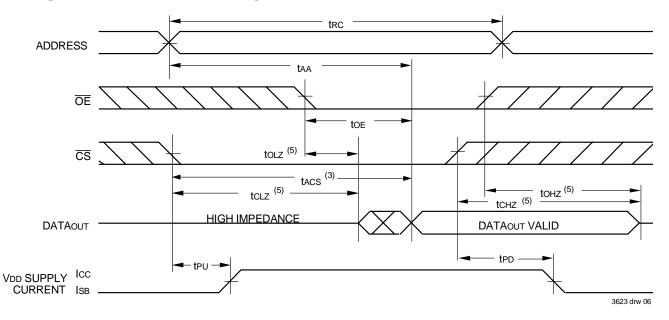
		71V428	3S/L10 ⁽²⁾	71V428S/L12		71V428S/L15		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
READ CYCLI	E					•		
trc	Read Cycle Time	10		12		15		ns
taa	Address Access Time		10		12		15	ns
tacs	Chip Select Access Time		10		12		15	ns
tclz ⁽¹⁾	Chip Select to Output in Low-Z	4		4		4		ns
tcHz ⁽¹⁾	Chip Deselect to Output in High-Z		5		6		7	ns
toe	Output Enable to Output Valid		5		6		7	ns
tolz ⁽¹⁾	Output Enable to Output in Low-Z	0		0		0		ns
tohz ⁽¹⁾	Output Disable to Output in High-Z		5		6		7	ns
toн	Output Hold from Address Change	4		4		4		ns
tpu ⁽¹⁾	Chip Select to Power Up Time	0		0		0		ns
tpd ⁽¹⁾	Chip Deselect to Power Down Time		10		12		15	ns
WRITE CYCL	E					•	•	<u>.</u>
twc	Write Cycle Time	10		12		15		ns
taw	Address Valid to End of Write	8		8		10		ns
tcw	Chip Select to End of Write	8		8		10		ns
tas	Address Set-up Time	0		0		0		ns
twp	Write Pulse Width	8		8		10		ns
twr	Write Recovery Time	0		0		0		ns
tow	Data Valid to End of Write	6		6		7		ns
tdн	Data Hold Time	0		0		0		ns
tow ⁽¹⁾	Output Active from End of Write	3		3		3		ns
twHz ⁽¹⁾	Write Enable to Output in High-Z		6		7		7	ns

NOTES:

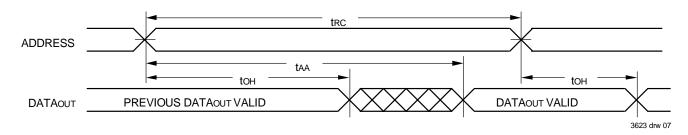
1. This parameter guaranteed with the AC load (Figure 2) by device characterization, but is not production tested.

2. 0°C to +70°C temperature range only for low power 10ns (L10) speed grade.

Timing Waveform of Read Cycle No. 1⁽¹⁾



Timing Waveform of Read Cycle No. 2^(1,2,4)



NOTES:

1. $\overline{\text{WE}}$ is HIGH for Read Cycle.

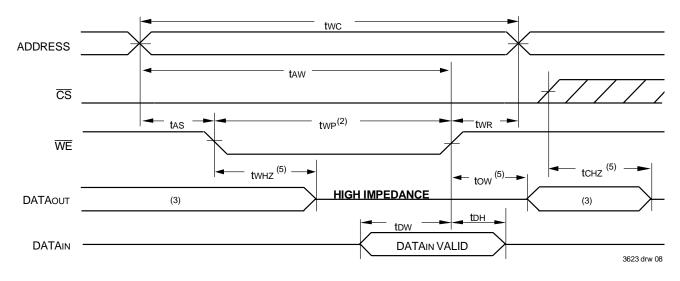
2. Device is continuously selected, \overline{CS} is LOW.

3. Address must be valid prior to or coincident with the later of CS transition LOW; otherwise taa is the limiting parameter.

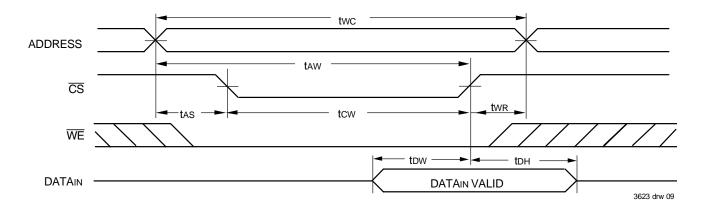
4. \overline{OE} is LOW.

5. Transition is measured $\pm 200 \text{mV}$ from steady state.

Timing Waveform of Write Cycle No.1 (WE Controlled Timing)^(1,2,4)



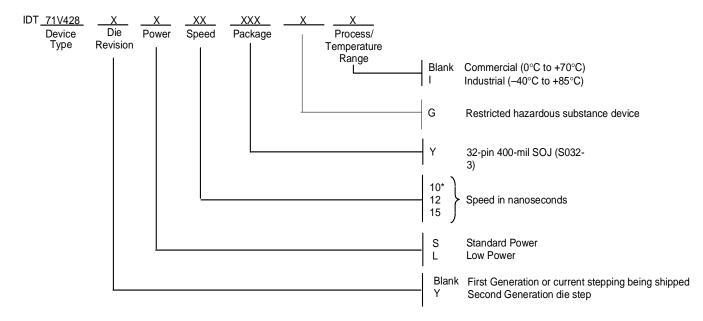
Timing Waveform of Write Cycle No.2 (CS Controlled Timing)^(1,4)



NOTES:

- 1. A write occurs during the overlap of a LOW \overline{CS} and a LOW \overline{WE} .
- OE is continuously HIGH. If during a WE controlled write cycle OE is LOW, twp must be greater than or equal to twHz + tow to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If OE is HIGH during a WE controlled write cycle, this requirement does not apply and the minimum write pulse is as short as the specified twp.
- 3. During this period, I/O pins are in the output state, and input signals must not be applied.
- 4. If the CS LOW transition occurs simultaneously with or after the WE LOW transition, the outputs remain in a high-impedance state.
- 5. Transition is measured ±200mV from steady state.

Ordering Information



* Commercial only for low power (L10) speed grade.

3623 drw 10

Datasheet Document History

8/31/99		Updated to new format
	Pg. 2	Added footnote for VHC in Truth Table
	Pg. 4	Added footnote on jig and scope capacitance in Figure 2
	Pg. 7	Revised footnote on Write Cycle No. 1 diagram
	Pg. 9	Added Datasheet Document History
9/29/99	Pg. 1–9	Added Industrial temperature range offerings
11/26/02	Pg. 8	Updated ordering information for die revision
07/31/03	Pg. 8	Updated note, L10 speed grade commercial temperature only and updated die stepping from YF to Y.
09/30/04	Pg. 8	Added "Restricted hazardous substance device" to ordering information.



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